PIN 1
INDEX AREA

4

A

0.1 C
2X

DETAIL G

M

4

B

0.1 C
2X

M

2.75
2.45

0.1 C A B

EXPOSED DIE
ATTACH PAD

19 24

DETAIL M
PIN 1 INDEX

18 1

0.25

2.75
2.45

0.1 C A B

20X 0.5

13 6

12 7

DETAIL N

24X 0.5
0.3

24X 0.30
0.18

0.1 Ⓜ C A B
0.05 Ⓜ C

VIEW M−M

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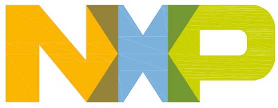
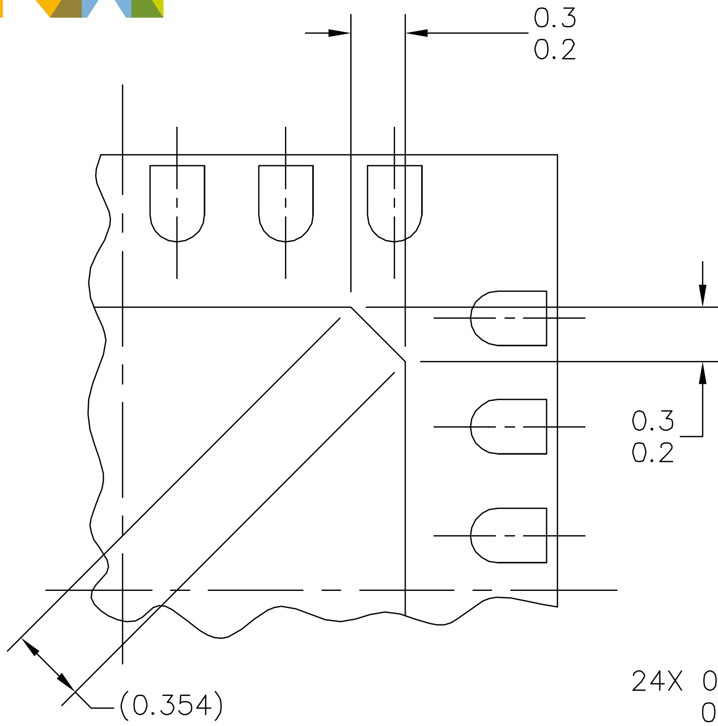
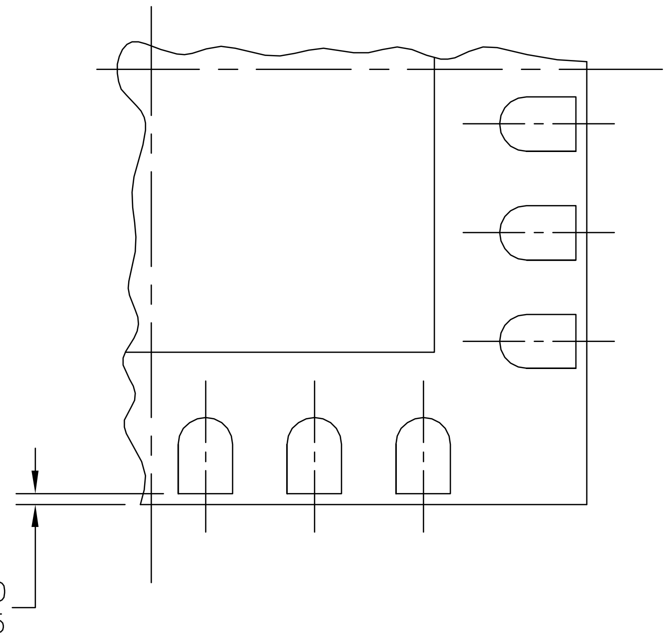
TITLE: THERMALLY ENHANCED QUAD FLAT NON−LEADED PACKAGE (QFN) 24 TERMINAL, 0.5 PITCH (4 X 4 X 1)	DOCUMENT NO: 98ARL10577D	REV: C
	STANDARD: NON−JEDEC	
	SOT616−5	04 MAR 2016

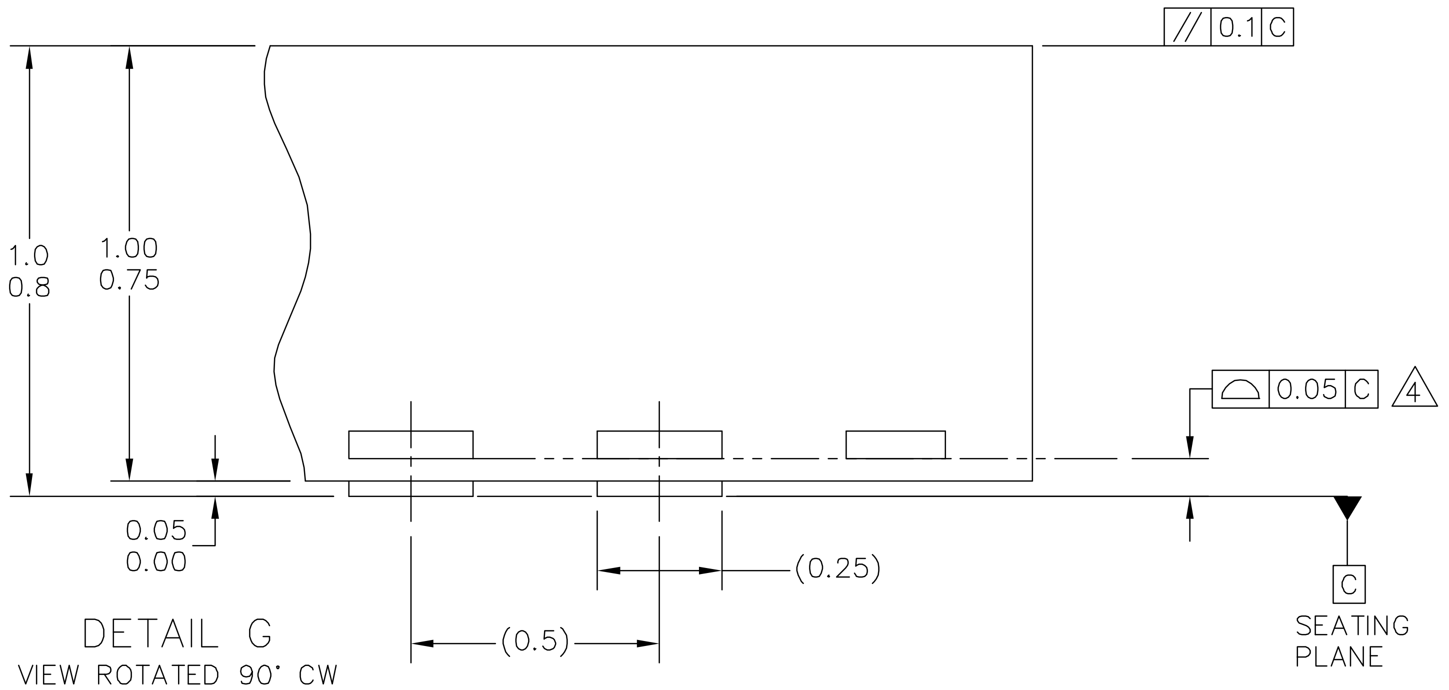




DETAIL M
PIN 1 BACKSIDE IDENTIFIER



DETAIL N
CORNER CONFIGURATION



DETAIL G
VIEW ROTATED 90° CW

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MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
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	STANDARD: NON-JEDEC
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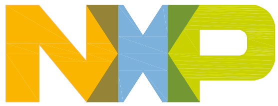
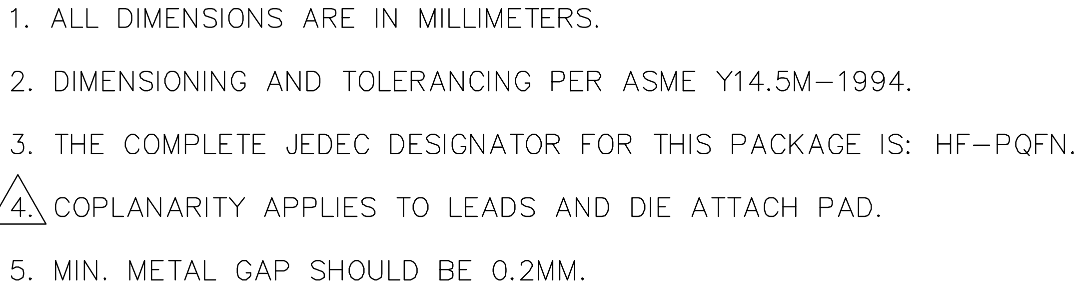


NOTES:



1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4. (triangle) COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP SHOULD BE 0.2MM.

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